

ABSTRACT

(OBJECT) The object is to provide a lightened semiconductor device and a manufacturing method thereof by pasting a layer to be peeled to various base materials.

(MEANS FOR SOLVING THE PROBLEM) In the present invention, a layer to be
5 peeled is formed on a substrate, then a seal substrate provided with an etching stopper
film is pasted with a binding material on the layer to be peeled, followed by removing
only the seal substrate by etching or polishing. The remaining etching stopper film is
functioned as a blocking film. In addition, a magnet sheet may be pasted as a pasting
member.